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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Toshiaki TAGAWA et al.
Serial No : Not Yet Assigned (National Stage of PCT/JP00/01563)
Filed : Concurrently Herewith (International Filing Date March 15, 2000)
For : LIGAND-BONDED COMPLEX

PRELIMINARY AMENDMENT

Commissioner of Patents and Trademarks
Washington, D.C. 20231

Sir:

Prior to calculation of the filing fees and the examination of the above-identified patent application on the merits, the Examiner is respectfully requested to amend the claims as follows:

IN THE CLAIMS

Please amend the claims as follows (a marked-up copy of the claim amendments is provided as an attachment to this Amendment):

4. (Amended-Clean Text) The ligand-bonded complex according to claim 1, wherein the ligand is directly bonded to the microparticle.